



Product Change Notification

106982 - 00

Information in this document is provided in connection with Intel products. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Intel's Terms and Conditions of Sale for such products, Intel assumes no liability whatsoever, and Intel disclaims any express or implied warranty, relating to sale and/or use of Intel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Intel products are not intended for use in medical, life saving, or life sustaining applications. Intel may make changes to specifications and product descriptions at any time, without notice.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2006. Other names and brands may be claimed as the property of others.

Celeron, Centrino, Intel, the Intel logo, Intel Core, Intel NetBurst, Intel NetMerge, Intel NetStructure, Intel SingleDriver, Intel SpeedStep, Intel StrataFlash, Intel Viiv, Intel XScale, Itanium, MMX, Paragon, PDCharm, Pentium, and Xeon are trademarks or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries.

Learn how to use Intel Trade Marks and Brands correctly at <http://www.intel.com/intel/legal/tmusage2.htm>.



Product Change Notification

Change Notification #: 106982 - 00
Change Title: Intel NetStructure(R) MPCMM0002Q Chassis Management Module, PCN 106982-00, Product Design, Change to Gasket, change to components
Date of Publication: November 08, 2006

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Nov 24, 2006
---	--------------

Description of Change to the Customer:

1. Changes to resistor values at location RP1 and R1 to improve design margin of maximum current allowed through LEDs.
2. Change in foam gasket to reduce the risk of broken adhesive tape during assembly process.

Customer Impact of Change and Recommended Action:

1. No impact to customer.
2. No impact to customer.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Pre Change PBA	Post Change Product Code	Post Change MM#	Post Change TA	Post Change PBA
MPCMM0002Q	875468	D52412-002	D37185-202	MPCMM0002Q	875468	D52412-003	D37185-203

Reference Documents / Attachments:

Document: _____ **Location #:** _____

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 8, 2006	00	Originally Published PCN